

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC6701DxxxPR-G  
Typical Mass: 53 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.617	Silicon	11600	7440-21-3
Leadframe	24.392	Copper	460200	7440-50-8
	0.016	Tin	300	7440-31-5
	0.218	Silver	4100	7440-22-4
Die attach	0.126	Silver	2400	7440-22-4
	0.032	Epoxy	600	—
Bonding wire	0.023	Gold	400	7440-57-5
Resin	23.500	Silica	443400	60676-86-0
	1.917	Epoxy resin	36200	—
	1.384	Phenol resin	26100	—
	0.375	Metal hydroxide	7100	—
Plating	0.400	Tin	7500	7440-31-5

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."